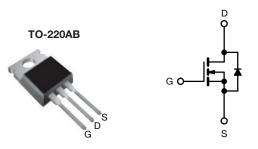
Vishay Siliconix

E Series Power MOSFET

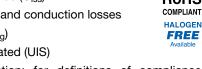


N-Channel	MOSFET
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PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	550			
R _{DS(on)} max. at 25 °C (Ω)	V _{GS} = 10 V	0.380		
Q _g max. (nC)	50			
Q _{gs} (nC)	6			
Q _{gd} (nC)	10			
Configuration	Single			

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Low gate charge (Qq)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912



APPLICATIONS

- Computing
 - PC silver box / ATX power supplies
- Lighting
 - Two stage LED lighting
- · Consumer electronics
- · Applications using hard switched topologies
 - Power factor correction (PFC)
 - Two switch forward converter
 - Flyback converter
- Switch mode power supplies (SMPS)

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free and halogen-free	SiHP12N50E-BE3 ^a
	SiHP12N50E-GE3

Note

a. "-BE3" denotes alternate manufacturing location

ABSOLUTE MAXIMUM RATINGS (T_C	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V _{DS}	500	
Gate-source voltage			V_{GS}	± 30	V
Continuous drain current (T _J = 150 °C)	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		10.5	
		T _C = 100 °C	ID	6.6	Α
Pulsed drain current ^a	a			21	
Linear derating factor				0.91	W/°C
Single pulse avalanche energy b			E _{AS}	103	mJ
Maximum power dissipation			P_{D}	114	W
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C
Drain-source voltage slope	T _J = 125 °C		-1) //-14	70	1//
Reverse diode dV/dt ^d			dV/dt	27	V/ns
Soldering recommendations (peak temperature) ^c	For 10 s			300	°C

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_a = 25 Ω , I_{AS} = 2.7 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	-	62	°C/W	
Maximum junction-to-case (drain)	R_{thJC}	-	1.1	C/ VV	

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT		
Static		-		"					
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		500	-	-	V		
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 1 mA		-	0.60	-	V/°C		
Gate-source threshold Voltage (N)	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$		2.0	-	4.0	V		
Cata agura laglaga		V _{GS} = ± 20 V		V _{GS} = ± 20 V		-	-	± 100	nA
Gate-source leakage	I _{GSS}	\	$V_{GS} = \pm 30 \text{ V}$		-	± 1	μΑ		
Zoro goto voltago drain ourrent	1	V _{DS} = 500 V, V _{GS} = 0 V		-	-	1			
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 400 \text{ V}$, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA		
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 6 A	-	0.330	0.380	Ω		
Forward transconductance	9 _{fs}	V _{DS} = 30 V, I _D = 6 A		-	3.1	-	S		
Dynamic				•	•				
Input capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ f = 1 MHz		-	886	-	pF		
Output capacitance	C _{oss}			-	52	-			
Reverse transfer capacitance	C _{rss}			-	6	-			
Effective output capacitance, energy related ^a	C _{o(er)}	$V_{DS} = 0 \text{ V to } 400 \text{ V}, V_{GS} = 0 \text{ V}$		-	45	-			
Effective output capacitance, time related ^b	C _{o(tr)}			-	131	-			
Total gate charge	Qg			-	25	50			
Gate-source charge	Q_{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 6 \text{ A}, V_{DS} = 400 \text{ V}$		6	-	nC		
Gate-drain charge	Q _{gd}			-	10	-	1		
Turn-on delay time	t _{d(on)}	V _{DD} = 400 V, I _D = 6 A,		-	13	26			
Rise time	t _r			-	16	32			
Turn-off delay time	t _{d(off)}	V _{GS} =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		29	58	ns -		
Fall time	t _f	1		-	12	24			
Gate input resistance	R_g	f = 1 MHz, open drain		-	0.92	-	Ω		
Drain-Source Body Diode Characteristic	s								
Continuous source-drain diode current	Is	MOSFET symbol showing the integral reverse p - n junction diode		-	-	10.5			
Pulsed diode forward current	I _{SM}			-	-	21	A		
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 7.5 A, V _{GS} = 0 V		-	-	1.2	V		
Reverse recovery time	t _{rr}	-		-	244	-	ns		
Reverse recovery charge	Q _{rr}	$T_J = 25$ °C, $I_F = I_S = 6$ A, $dI/dt = 100$ A/ μ s, $V_R = 25$ V		-	2.5	-	μC		
Reverse recovery current	I _{RRM}			_	19	_	A		

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

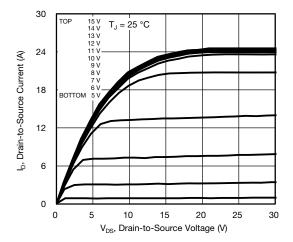


Fig. 1 - Typical Output Characteristics

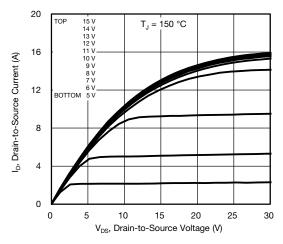


Fig. 2 - Typical Output Characteristics

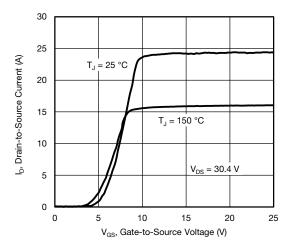


Fig. 3 - Typical Transfer Characteristics

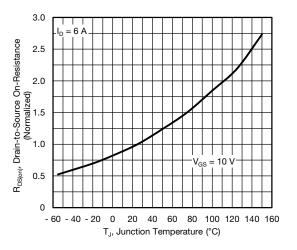


Fig. 4 - Normalized On-Resistance vs. Temperature

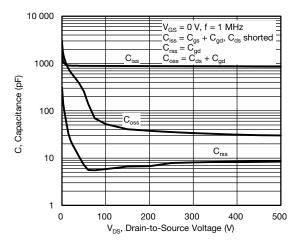


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

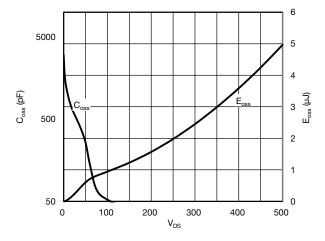


Fig. 6 - Coss and Eoss vs. VDS



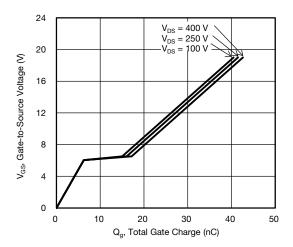


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

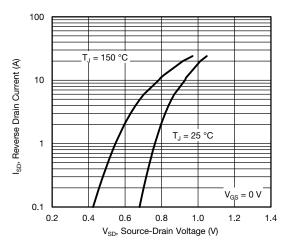


Fig. 8 - Typical Source-Drain Diode Forward Voltage

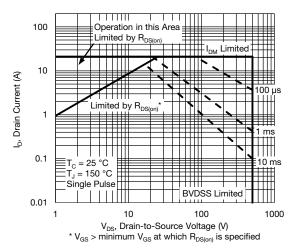


Fig. 9 - Maximum Safe Operating Area

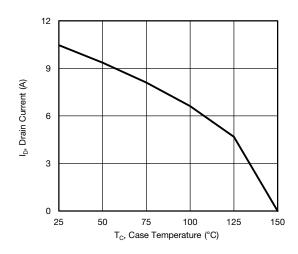


Fig. 10 - Maximum Drain Current vs. Case Temperature

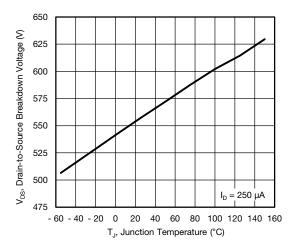


Fig. 11 - Temperature vs. Drain-to-Source Voltage



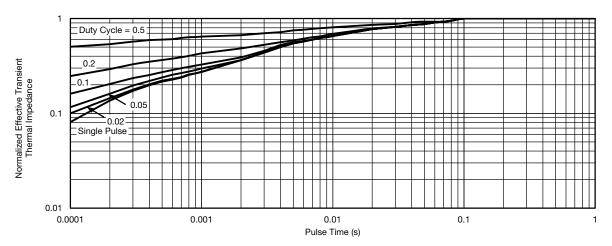


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

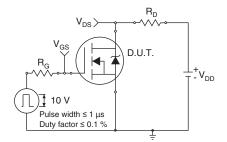


Fig. 13 - Switching Time Test Circuit

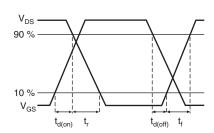


Fig. 14 - Switching Time Waveforms

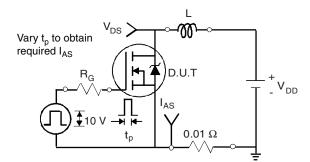


Fig. 15 - Unclamped Inductive Test Circuit

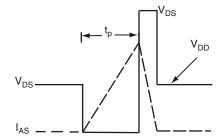


Fig. 16 - Unclamped Inductive Waveforms

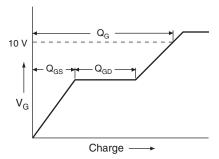


Fig. 17 - Basic Gate Charge Waveform

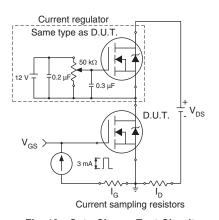
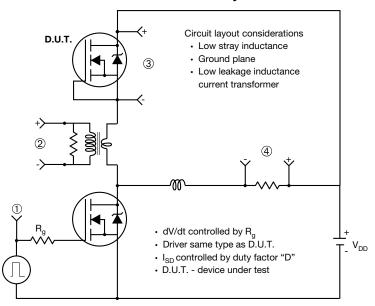


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



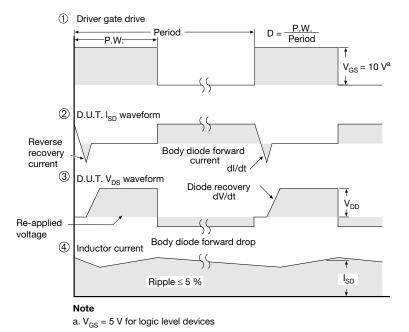


Fig. 19 - For N-Channel

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